PRESS RELEASE

Contact: Jan Vardaman
(512) 372-8887

FOR IMMEDIATE RELEASE
October 26, 2016

TechSearch International Analysis Shows CSP Growth Remains Strong

Despite a slowing growth rate for smartphones, the industry is experiencing strong growth for CSP packages such as QFNs and stacked die CSPs. TechSearch International's latest CSP market forecast shows an 8% CAGR from 2015 to 2020. One of the categories with the strongest growth is the quad flat no-lead (QFN) package with a CAGR of 8.6%. QFNs are a low-cost, low-profile package found in a wide range of products from automotive and industrial applications to mobile phones and wearable electronics. Power devices continue to drive growth for copper clip versions of the QFN. An analysis of the OSAT market in China provides insight into expansion plans and market share. New advanced packages such as JCAP's FO-WLP are highlighted.

The analysis is provided in the latest Advanced Packaging Update, a 45-page report with full references and an accompanying set of 36 PowerPoint slides. The report also examines trends in stacked die CSPs, laminate-substrate CSPs, and package-on-package (PoP) with a market forecast for each. PoP trends are analyzed, including the use of TSMC's FO-WLP for Apple's A10 application processor. A five-year market forecast for BGAs is also provided.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 17,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see http//www.techsearchinc.com.